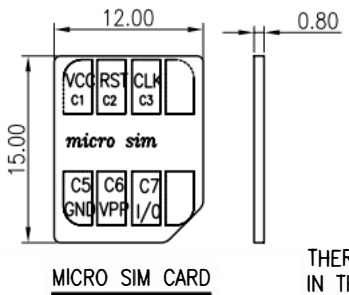


| SIM pin Assignment | |
|--------------------|------|
| PIN# | Name |
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |

NOTES:
 MATERIAL:
 Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:
 Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area

Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:1000M min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5°



■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

LXW 连兴旺电子(深圳)有限公司
 LXWCONV ELECTRONICS (SHENZHEN) CO., LTD

| | | |
|------------|-------------------------------------|-------------------------|
| F | PRODUCT SPEC. MICRO SIM | |
| TITLE: | 1.35H MICRO SIM CARD 6PIN PUSH PUSH | |
| PART NO. | CS-0025-06135 | |
| FILE NAME: | | |
| SCALE | 1:1 | UNIT:mm A4 SHEET:1 of 1 |

| | | General | Angle | 设计 | | | |
|----------|-----|--|-------------|--------|---------|-----------|--|
| | | X±0.50 | | DESIGN | Nicolas | 16'/08/20 | |
| | | .X±0.30 | .X'±3' | 校阅 | | | |
| | | .XX±0.20 | .XX'±2 | CHECK | Nicolas | 16'/08/20 | |
| | | GENERAL TOLERANCE UNLESS OTHERWISE NOTED | | 承认 | | | |
| 工程变更通知单号 | 版次 | 日期 | 说明 | 改变 | 承认 | | |
| REV | REV | DATE | DESCRIPTION | CHANGE | APPRO. | | |

A 16'/08/20 NEW RELEASE